

Brief Data Sheet

Issue 01

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Overview

Hi3516DV500 is an HD intelligent system-on-chip (SoC) tailored to the vision industry. This SoC provides up to two sensor inputs and optimum image processing capabilities, including 5M@30 fps image signal processing (ISP), AI-powered real-time noise reduction (NR), and a wide range of traditional image enhancement and processing algorithms, such as 2F wide dynamic range (WDR), multi-level NR, 6-DoF digital image stabilization (DIS), and Mono-Color-Fusion (MCF). It also allows for the access and processing of thermal infrared, structured-light, and time-of-flight (ToF) sensors.

Hi3516DV500 has a built-in quad-core Cortex-A55 processor, providing efficient, rich, and flexible CPU resources to meet customers' computing and control requirements.

Hi3516DV500 integrates an efficient neural network (NN) inference engine with up to 2 TOPS NN compute power, which supports mainstream NN frameworks.

With a stable and easy-to-use software development kit (SDK), Hi3516DV500 is set to facilitate mass production of customers' products.

Key Features

- Intelligent acceleration2 TOPS INT8 NN acceleration engine
- 5M@30 fps codec
 -H.265/H.264 encoding at 5M@30 fps
 -H.265/H.264 decoding at 5M@30 fps
- 2-channel 2M@30 fps MCF
- Al ISP
- USB 3.0 high-speed peripheral interface
- Ultra-fast image generation in Linux (300 ms)



Key Characteristics

Processor Core

- Dual-core Arm Cortex-A55@850 MHz
- 32 KB I-cache, 32 KB D-cache, and 256 KB L3 cache
- Neon acceleration and integrated floatingpoint unit (FPU)
- TrustZone

System-Level Acceleration Modules

- Hardware accelerated standard CRC32, CRC16, and CRC8 polynomial calculation unit
- Hardware accelerated high-speed direct memory access (DMA) module

Intelligent Video Analysis

- NN
 Complete APIs and toolchains
- Upgraded intelligent video engine (IVE)
 operators, including computer morphological
 operators for feature point detection,
 perimeters, optical flows, and more
- Upgraded depth processing unit (DPU)
 algorithm for the binocular depth image
 acceleration unit, supporting a resolution of
 up to 2048 x 2048 pixels, a parallax of up to
 224 pixels, and 720p@30 fps processing
 performance

Video Codec

- H.264 Baseline Profile/Main Profile/High Profile Level 5.1
- H.265 Main Profile Level 5.1
- Up to 6144 x 6144 H.264/H.265 codec resolution
- I-frames and P-frames
- Typical performance of H.264/H.265 multistream codec:
 - 2592 x 1944@30 fps (encoding) + 1920 x 1080@30 fps (encoding) + 720 x 480@30 fps (encoding)
 - 2592 x 1944@30 fps (encoding) + 720 x 480@30 fps (encoding) + 1920 x 1080@30 fps (decoding)

- 2592 x 1944@30 fps (decoding)
- On-screen display (OSD) overlay before encoding of eight regions
- CBR, VBR, AVBR, FixQp, and QpMap bit rate control modes
- Up to 80 Mbps output bit rate
- Encoding of eight regions of interest (ROIs)
- Mosaic encoding overlay on the video front end
- Digital watermark
- Perceptual video coding (PVC) for bitrate reduction
- JPEG baseline codec
- Up to 16384 x 16384 JPEG codec resolution
- Maximum JPEG performance:
 - Encoding: 2592 x 1944@60 fps (YUV420)
 - Decoding: 2592 x 1944@30 fps (YUV420)

ISP

- Synchronous processing of multiple sensors
- Adjustable 3A functions: automatic exposure (AE), automatic white balance (AWB), and automatic focus (AF)
- Fixed pattern noise (FPN)
- Defect pixel correction and lens shading correction
- 2-frame WDR, advanced local tone mapping, strong light suppression, and backlight compensation
- Multi-level three-dimensional noise reduction (3DNR)
- Image edge enhancement
- Dehaze
- Dynamic contrast improvement (DCI)
- 3D-LUT color adjustment
- Next-generation lens distortion correction
- Geometry correction of any shape such as fisheye
- 6-DoF DIS
- Gyro stabilization and rolling shutter correction
- Image mirroring, flipping, and rotation by 90 or 270 degrees
- NN-based real-time dynamic range



- compression (DRC), Bayer noise reduction (BNR), 3DNR, or demosaicing (DM) processing on images
- Dual-light fusion of mono and color images
- ISP adjustment tool on the PC

Video and Graphics Processing

- Graphics and image scaling by 1/15.5x to 16x
- Horizontal AVS
 - Two 1920 x 1080@30 fps inputs and up to 3840 x 1080@30 fps or 1920 x 2160@30 fps output
- Overlaying of video and graphics layers
- Color space conversion (CSC)

Video Input Interfaces

- 4-lane image sensor serial inputs and multiple interfaces such as MIPI, LVDS, sub-LVDS, and HiSPI
- Multiple combinations such as 4-lane and 2x2-lane modes, and up to 2-sensor inputs
- 8-/10-/12-/14-bit RGB Bayer DC timing video input and up to 148.5 MHz clock frequency
- BT.601, BT.656, and BT.1120 video input interfaces
- One to four YUV inputs through the MIPI virtual channels
- Access of mainstream CMOS level thermal imaging sensors
- Structured light module
- Continuous-wave (CW) ToF image sensor

Video Output Interfaces

- One BT.1120 or BT.656 output interface with up to 1920 x 1080@60 fps for BT.1120
- 6-/8-bit serial output or 16-/18-/24-bit RGB parallel output with up to 74.25 MHz frequency
- 4-lane MIPI DSI/CSI output with up to 1.8
 Gbps per lane and 1920 x 1080@60 fps
- Gamma correction and horizontal sharpening

Audio Interfaces and Processing

 Embedded audio codec, supporting 16-bit dual-channel differential voice inputs and dual-channel single-ended voice outputs

- One I²S interface, compatible with the multichannel time division multiplexing (TDM) transmission mode
- Eight digital mic array inputs
- Multi-protocol voice codec
- Audio 3A functions: AEC, ANR, and ALC

Security Isolation and Engines

- Secure boot
- REE and TEE hardware isolation based on TrustZone
- NN model and data protection
- Hardware-based AES128/256 symmetric encryption algorithms
- Hardware-based RSA3072/4096 signature verification algorithms
- Hardware-based ECC256/384/512 elliptic curve algorithms
- Hardware-based SHA-256/384/512 and HMAC_SHA256/384/512 algorithms
- Hardware-based SM2/3/4 Chinese cryptographic algorithms
- Hardware-based true random number generator (TRNG)
- 28-kbit one-time programming (OTP) storage space

Network Interface

- One GE interface:
 - RGMII and RMII modes
 - Acceleration units such as TCP segmentation offload (TSO), UDP fragmentation offload (UFO), and checksum offload engine (COE)

Peripheral Interfaces

- Two SDIO 3.0 interfaces
 - SDIO0 supports the secure digital extended capacity (SDXC) card with up to 2 TB storage.
 - SDIO1 supports the connection with a Wi-Fi module.
- One USB 3.0 interface
 - USB host-device switchover
- Power-on reset (POR) and external input reset



- Real-time clock (RTC) with independent power supply
- Simplified power-on and power-off control logic for SoC standby wakeup
- 4-channel low-speed analog-to-digital converters (LSADCs)
- Three-wire control interface dedicated for RGB small-sized displays
- Multiple UART, I²C, SPI, PWM, and GPIO interfaces

External Memory Interfaces

- DDR4, LPDDR4, and LPDDR4x interfaces
 - 2 x 16-bit DDR4
 - 1 x 32-bit LPDDR4 and LPDDR4x
 - Up to 2400 Mbps DDR4 rate
 - Up to 2400 Mbps LPDDR4 and LPDDR4x rate
 - Up to 4 GB storage
- SPI NOR and SPI NAND flash interfaces
 - 1-/2-/4-wire mode
 - 3-byte and 4-byte address modes for the SPI NOR flash
- eMMC 5.1 interface with up to 2 TB storage
- Booting from the eMMC, SPI NOR flash, or SPI NAND flash

SDK

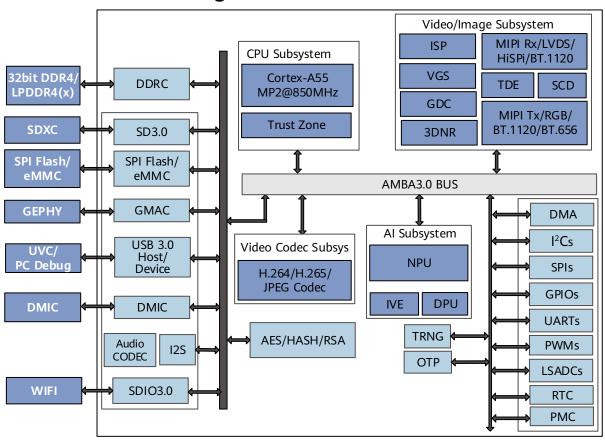
Linux 5.10 SDK

Physical Specifications

- Power consumption
 - 2 W typical power consumption (5Mp30 encoding + 2 TOPS)
- Operating voltage
 - Core voltage: 0.9 V
 - I/O voltage: 1.8 V or 3.3 V
 - DDR4, LPDDR4, and LPDDR4x interface voltages: 1.2 V, 1.1 V, and 0.6 V, respectively
- Package
 - RoHS, 15 mm x 15 mm FCCSP
 - 0.65 mm ball pitch

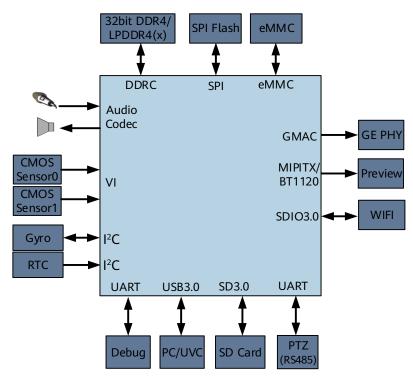


Functional Block Diagram





Hi3516DV500 HD Smart Vision SoC Solution





Acronyms and Abbreviations

3DNR three-dimensional noise reduction

AAC advanced audio coding

AE automatic exposure

AEC acoustic echo control

AES advanced encryption standard

AF automatic focus

ALC automatic level control

ANR adaptive noise reduction

API application programming interface

AVBR adaptive variable bit rate

AVS any view stitching

AWB automatic white balance

CAC chromatic aberration correction

CBR constant bit rate

CMOS complementary metal-oxide-semiconductor

CV computer vision

codec coder/decoder

COE checksum offload engine

CSI camera serial interface

DC digital camera

DCI dynamic contrast improvement

DDR double data rate

DDRC double data rate controller

DIS digital image stabilization

DPU depth processing unit

DSI display serial interface



DSP digital signal processor

DMIC digital microphone

DMA direct memory access

ECC error-correcting code

eMMC embedded multimedia card

EP endpoint

FCCSP flip-chip scale package

FPN fixed pattern noise

FPU floating-point unit

GE gigabit Ethernet

GMAC Gigabit Ethernet Media Access Controller

GPIO general-purpose input/output

GUI graphical user interface

HD high definition

HiSPI high-speed serial pixel interface

I²C inter-integrated circuit

I²S inter-IC sound

ISP image signal processor

IVE intelligent video engine

LCD liquid crystal display

LGDC lens geometric distortion correction

LPDDR low-power double data rate

LSADC low-speed analog-to-digital converter

LUT lookup table

LVDS low-voltage differential signaling

MAU matrix arithmetic unit

MCU microcontroller unit

mic microphone



MIPI mobile industry processor interface

NR noise reduction

OSD on-screen display

OTP one-time programming

PIP picture-in-picture

POR power-on reset

PWM pulse-width modulation

RAM random access memory

RC root complex

RGB red-green-blue

RGMII reduced gigabit media-independent interface

RMII reduced media-independent interface

RoHS restriction of hazardous substances

ROI region of interest

RSA Rivest-Shamir-Adleman

RNG random number generator

RTC real-time clock

SD secure digital

SDIO secure digital input/output

SDK software development kit

SDRAM synchronous dynamic random access memory

SDXC secure digital extended capacity

SMP symmetric multiprocessing

SoC system-on-chip

SPI serial peripheral interface

SCD start code detect

TDM time division multiplexing

TOPS Tera Operations Per Second



TSO TCP segmentation offload

TX transmit

UART universal asynchronous receiver transmitter

USB Universal Serial Bus

UFO UDP fragmentation offload

VBR variable bit rate

VI video input

VO video output

VQE voice quality enhancement

WDR wide dynamic range